

# Press Release: Industry News

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For Immediate Release



## Technical Presentations at the Upcoming SMTA Capital Chapter Expo on August 23<sup>rd</sup>

**August 15, 2018** - The SMTA Capital Chapter is holding its upcoming Capital Expo and Tech Forum at Johns Hopkins University / Applied Physics Lab, Kossiakoff Center, 11100 Johns Hopkins Road, Laurel, MD 20723, on Thursday, August 23<sup>rd</sup>.

We are excited to provide our attendees with another year of strong technical presentations focusing on the most relevant industry topics. Our keynote speaker, Geoffrey Doyle of Jabil Circuit, will be giving his presentation “Additive Manufacturing” at 9:45 AM. Additional technical presentations include:

Dr. Alfred Zinn, Kurion Inc., presenting “Versatile Nanocopper Materials-System for High Performance Printing, Assembly and Packaging.” Dr. Alfred Zinn is founder and CEO of Kuprion Inc., a materials company incorporated in Delaware, 2016. Kuprion is principally engaged in the manufacture and application of nanomaterials for a wide variety of applications such as surface mount technology, printed circuit board assembly with special focus on copper-based nanomaterials. A nanocopper-based interconnect and die-bonding material has been developed as a robust, high-performance alternative to solder. This solder-free nanocopper material overcomes a fundamental limitation of traditional solders in which the processing temperature imposes an upper ceiling for maximum allowable thermal operating conditions.

MB Allen, KIC, presenting “Industry 4.0 the Next Industrial Revolution – The Smart Factory.” MB Allen is the Product Manager for KIC. As such she coordinates the advancement of new products and features to accommodate customer needs as KIC adds to its portfolio for the electronics industry. Industry 4.0 is a name for the current trend of automation and data exchange in manufacturing technologies. It includes cyber-physical systems, the Internet of Things (IoT), cloud computing and cognitive computing. I4.0 is commonly referred to as the fourth industrial revolution and essentially creates a Smart Factory.

Kim Flanagan, Indium Corporation, presenting “Avoiding the Pitfalls of Voiding in PCB Assemblies.” Kim Flanagan is a Technical Support Engineer providing technical support, including guidance and recommendations to customers related to process steps, equipment, techniques and materials. In addition, she delivers technical training to staff and industry partners. Kim is a Certified SMT Process Engineer recognized by the SMTA. Bottom termination component use has increased very quickly throughout the last decade. Typical assemblies now have many of these components, often varying types of BTCs on one assembly. What is there to do when one or more starts to show increased variation within the same process? Many investigations have been conducted to find materials that offer the lowest voiding in large ground plane solder joints. In addition, there are many process modifications that have been proposed over the last decade to alleviate voiding in BTC components. These include but are not limited to: pad design, pad patterning, stencil design, via positioning, solid solder addition and reflow profile optimization. Furthermore, improved pad design strategies have been proven in the industry. IPC committees are updating the recommendations for design and implementation of BTCs including big changes to the IPC-7093. This presentation will discuss how these strategies can be used to minimize voiding and ensure robust BTC assemblies.

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Please join us for this great networking and free educational event. Registration opens at 7:30 AM and the first technical presentation will start at 8:30 AM. A complimentary lunch is included on the show floor and exhibits are open from 9:00 AM until 3:00 PM.

To register online to attend or exhibit, please visit <http://www.smta.org/expos/#capital>.

## **About Surface Mount Technology Association (SMTA)**

The SMTA membership is an international network of professionals who build skills, share practical experience and develop solutions in electronic assembly technologies, including microsystems, emerging technologies, and related business operations. For more information or to join, please visit

[www.smta.org](http://www.smta.org).

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Other Information:

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